

SIP module for P2P replacement

China Power Design Service

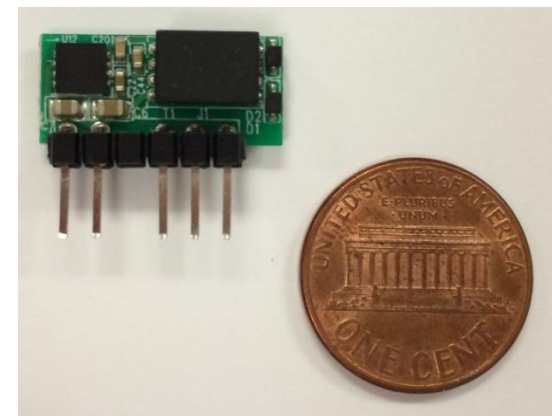
Reference Design	TI Parts	V _{in}	P _o	Output	Topology	Eff.
<u>PMP4394</u>	LM25018	24V ± 10%	1W	±5V@100mA	Flybuck	>84%
<u>PMP4401</u>	LM25018	12V ± 10%	1W	±5V@100mA	Flybuck	82%@12Vin
<u>PMP4412</u>	LM25018	24V ± 10%	1W	+5V@200mA	Flybuck	>83%
<u>PMP4413</u>	LM25018	24V ± 10%	1W	±15V@33mA	Flybuck	>83%
<u>PMP4414</u>	LM25017	24V ± 10%	2W	+15V@83mA -15V@50mA	Flybuck	>87%
<u>PMP4415</u>	LM25017	24V ± 10%	3W	+15V@150mA -15V@50mA	Flybuck	>84%

Features

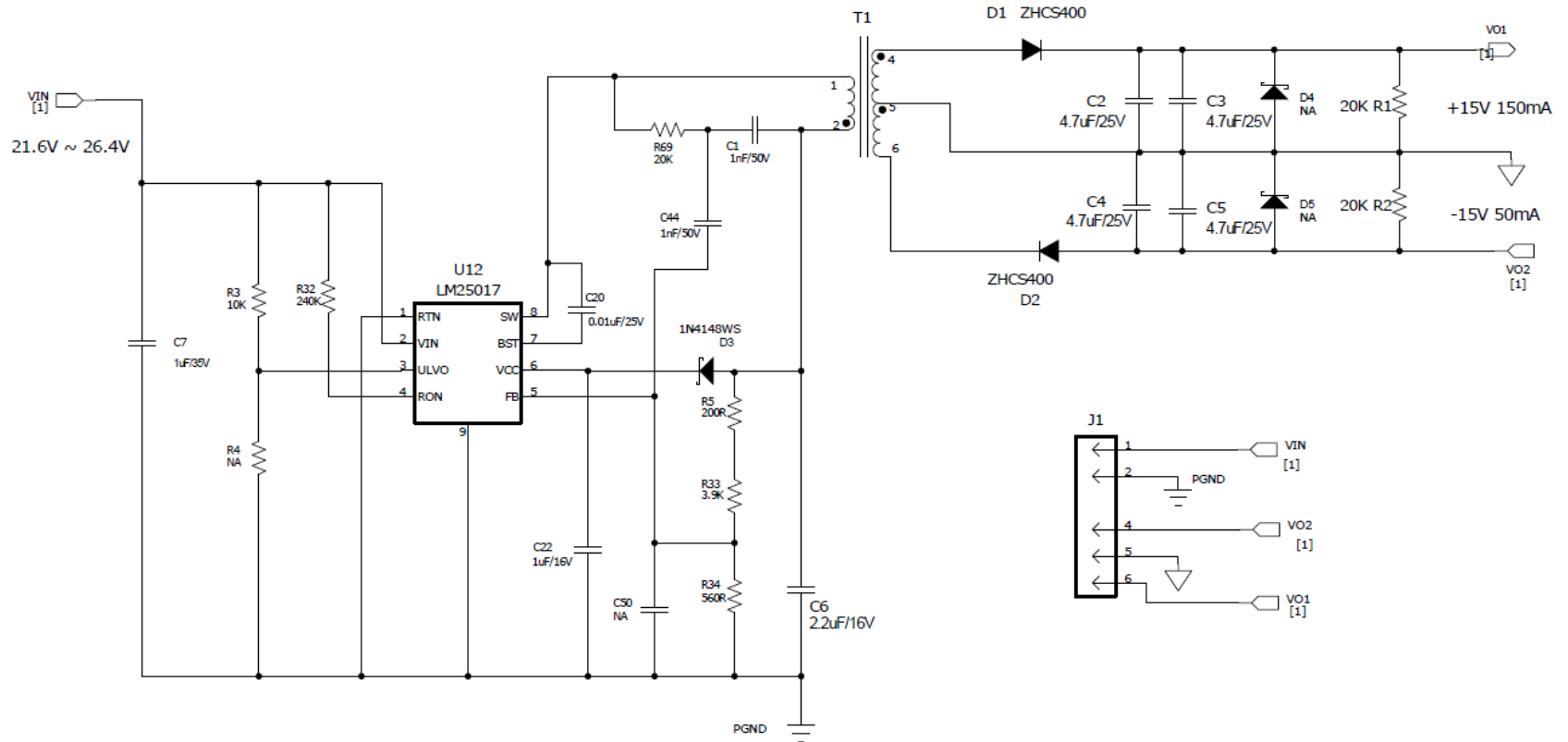
- Isolated interface **Flybuck™** power supply with single or couple channel output;
- 1500Vdc Isolation;
- Good line and load regulation;
- Low cost, minimized component numbers;
- Industrial Compatible Pin out ;
- Small PCB size, 19.8mm*9mm*5.8mm , 2 layer design

Application

- PLC, metering etc. Industrial
- Telecom
- Aux power



3W SIP Module Schematic



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